

**HIGH ISOLATION VOLTAGE
SINGLE TRANSISTOR TYPE
MULTI PHOTOCOUPLER SERIES**

--NEPOC Series--

DESCRIPTION

The PS2561-1 is optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2561-1 is in a plastic DIP (Dual In-line Package) and the PS2561L-1 is lead bending type (Gull-wing) for surface mount.

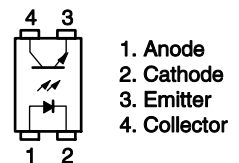
The PS2561L1-1 is lead bending type for long creepage distance.

The PS2561L2-1 is lead bending type for long creepage distance (Gull-wing) for surface mount.

FEATURES

- High Isolation voltage ($BV = 5\,000\text{ Vr.m.s.}$)
- High collector to emitter voltage ($V_{CEO} = 80\text{ V}$)
- High current transfer ratio ($CTR = 200\% \text{ TYP.}$)
- High-speed switching ($t_r = 3\ \mu\text{s TYP.}$, $t_f = 5\ \mu\text{s TYP.}$)
- Ordering number of taping product: PS2561L-1-E3, E4, F3, F4, PS2561L2-1-E3, E4
- Safety standards
 - UL approved: No. E72422
 - CSA approved: No. CA 101391
 - BSI approved: No. 7112/7420
 - SEMKO approved: No. 303059, 307244
 - NEMKO approved: No. P03200272, P03200747
 - DEMKO approved: No. 312341, 312340
 - FIMKO approved: No. FI 10620, FI 11898
- DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40008862 (Option)

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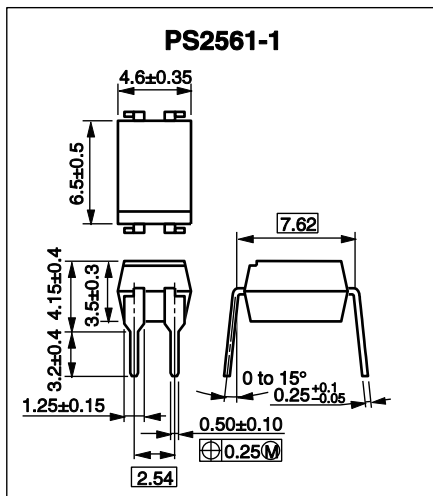
**PIN CONNECTION
(Top View)****APPLICATIONS**

- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

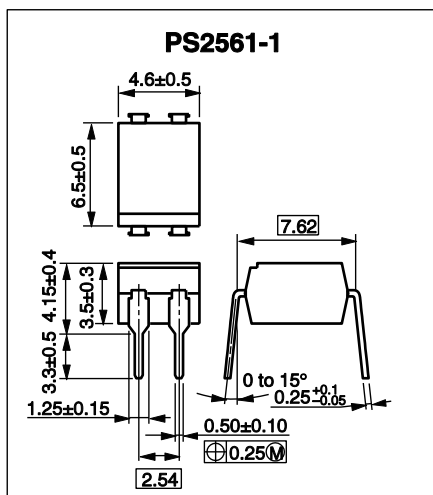
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PACKAGE DIMENSIONS (UNIT : mm)

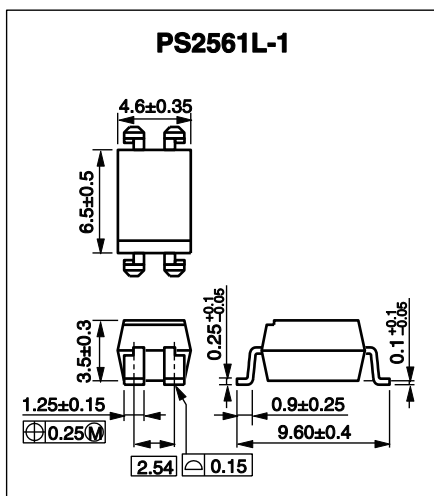
DIP Type (New package)



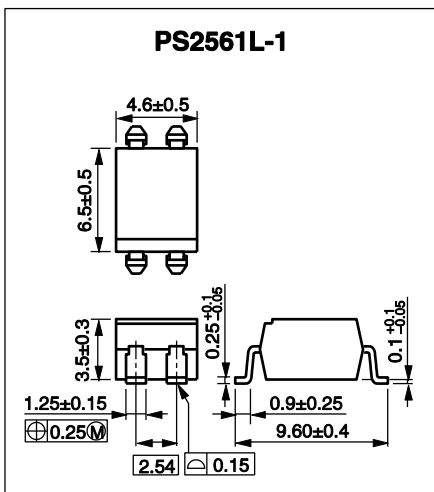
DIP Type



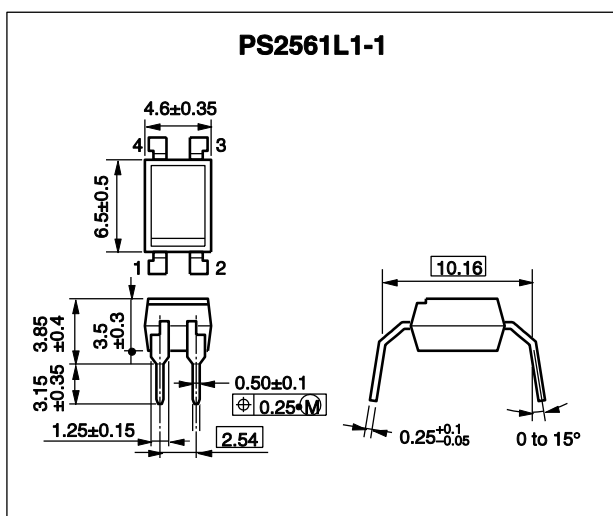
Lead Bending Type (New package)



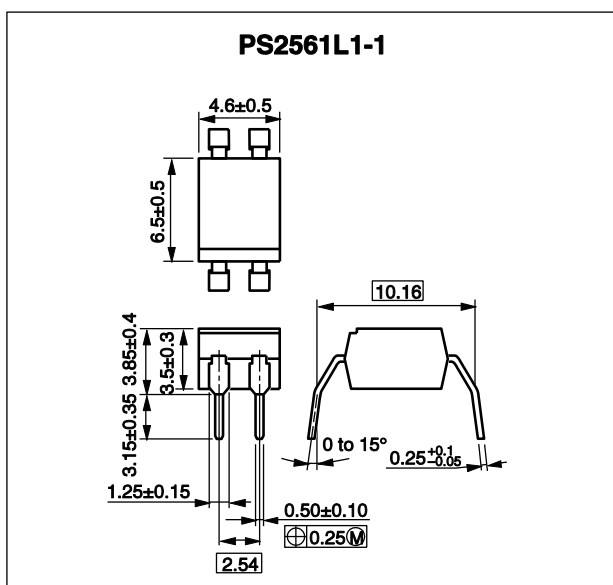
Lead Bending Type



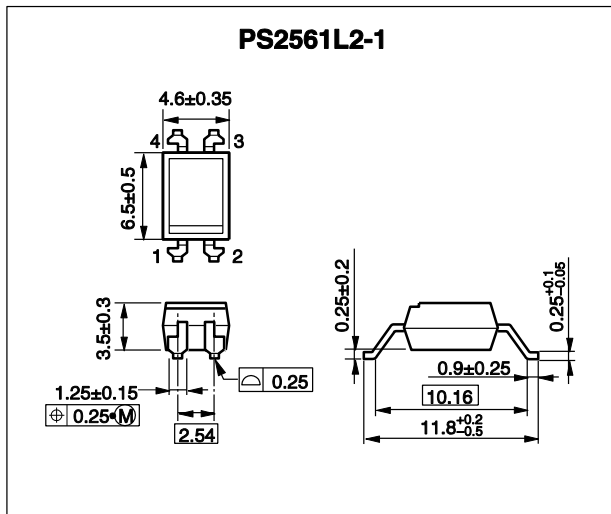
Lead Bending Type For Long Creepage Distance (New Package)



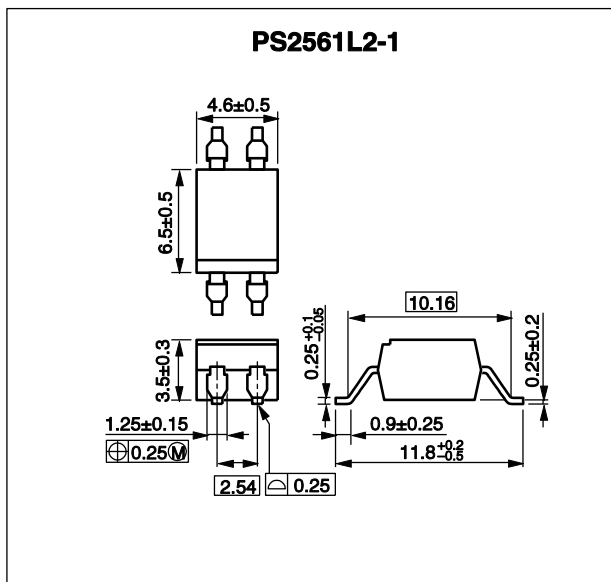
Lead Bending Type For Long Creepage Distance



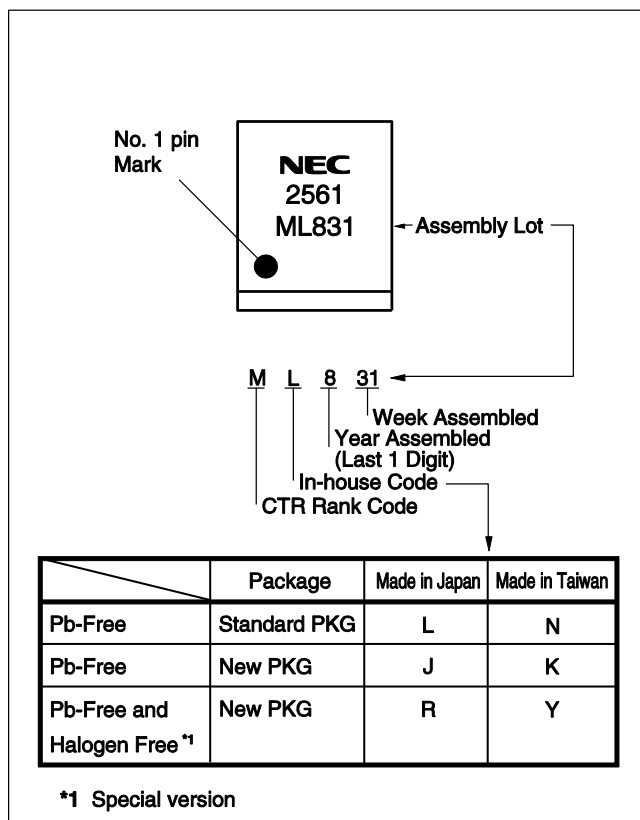
Lead Bending Type For Long Creepage Distance (Gull-Wing) (New Package)



Lead Bending Type For Long Creepage Distance (Gull-Wing)



<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS2561-1	PS2561-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL, CSA, BSI, NEMKO, SEMKO, DEMKO, FIMKO approved)	PS2561-1
PS2561L-1	PS2561L-1-A				
PS2561L1-1	PS2561L1-1-A				
PS2561L2-1	PS2561L2-1-A				
PS2561L-1-E3	PS2561L-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561L-1-E4	PS2561L-1-E4-A				
PS2561L-1-F3	PS2561L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2561L-1-F4	PS2561L-1-F4-A				
PS2561L2-1-E3	PS2561L2-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561L2-1-E4	PS2561L2-1-E4-A				
PS2561-1-V	PS2561-1-V-A		Magazine case 100 pcs	DIN EN60747-5-2 (VDE0884 Part2) approved products (Option)	
PS2561L-1-V	PS2561L-1-V-A				
PS2561L1-1-V	PS2561L1-1-V-A				
PS2561L2-1-V	PS2561L2-1-V-A				
PS2561L-1-V-E3	PS2561L-1-V-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561L-1-V-E4	PS2561L-1-V-E4-A				
PS2561L-1-V-F3	PS2561L-1-V-F3-A		Embossed Tape 2 000 pcs/reel		
PS2561L-1-V-F4	PS2561L-1-V-F4-A				
PS2561L2-1-V-E3	PS2561L2-1-V-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561L2-1-V-E4	PS2561L2-1-V-E4-A				
PS2561-1	PS2561-1Y-A	Special version (Pb-Free and Halogen Free)	Magazine case 100 pcs	Standard products (UL, CSA, BSI, NEMKO, SEMKO, DEMKO, FIMKO approved)	PS2561-1
PS2561L-1	PS2561L-1Y-A				
PS2561L1-1	PS2561L1-1Y-A				
PS2561L2-1	PS2561L2-1Y-A				
PS2561L-1-F3	PS2561L-1Y-F3-A		Embossed Tape 2 000 pcs/reel		
PS2561L2-1-E3	PS2561L2-1Y-E3-A		Embossed Tape 1 000 pcs/reel		
PS2561-1-V	PS2561-1Y-V-A		Magazine case 100 pcs	DIN EN60747-5-2 (VDE0884 Part2) approved products (Option)	
PS2561L-1-V	PS2561L-1Y-V-A				
PS2561L1-1-V	PS2561L1-1Y-V-A				
PS2561L2-1-V	PS2561L2-1Y-V-A				
PS2561L-1-V-F3	PS2561L-1Y-V-F3-A		Embossed Tape 2 000 pcs/reel		
PS2561L2-1-V-E3	PS2561L2-1Y-V-E3-A		Embossed Tape 1 000 pcs/reel		

***1** For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage	V_R	6	V
	Forward Current (DC)	I_F	80	mA
	Power Dissipation Derating	$\Delta P_D/^\circ\text{C}$	1.5	mW/ $^\circ\text{C}$
	Power Dissipation	P_D	150	mW
	Peak Forward Current ^{*1}	I_{FP}	1	A
Transistor	Collector to Emitter Voltage	V_{CEO}	80	V
	Emitter to Collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Power Dissipation Derating	$\Delta P_C/^\circ\text{C}$	1.5	mW/ $^\circ\text{C}$
	Power Dissipation	P_C	150	mW
Isolation Voltage ^{*2}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T_A	-55 to +100	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^\circ\text{C}$

***1** PW = 100 μs , Duty Cycle = 1%

***2** AC voltage for 1 minute at $T_A = 25^\circ\text{C}$, RH = 60% between input and output

Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$		1.17	1.4	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5	μA
	Terminal Capacitance	C_t	$V = 0\text{ V}, f = 1.0\text{ MHz}$		50		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	$V_{CE} = 80\text{ V}, I_F = 0\text{ mA}$			100	nA
Coupled	Current Transfer Ratio (I_C/I_F)* ¹	CTR	$I_F = 5\text{ mA}, V_{CE} = 5\text{ V}$	80	200	400	%
	Collector Saturation Voltage	$V_{CE(sat)}$	$I_F = 10\text{ mA}, I_C = 2\text{ mA}$			0.3	V
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1.0\text{ kV}_{DC}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}, f = 1.0\text{ MHz}$		0.5		pF
	Rise Time* ²	t_r	$V_{CC} = 10\text{ V}, I_C = 2\text{ mA}, R_L = 100\text{ }\Omega$		3		μs
	Fall Time* ²	t_f			5		

*1 CTR rank

L : 200 to 400 (%)

M : 80 to 240 (%)

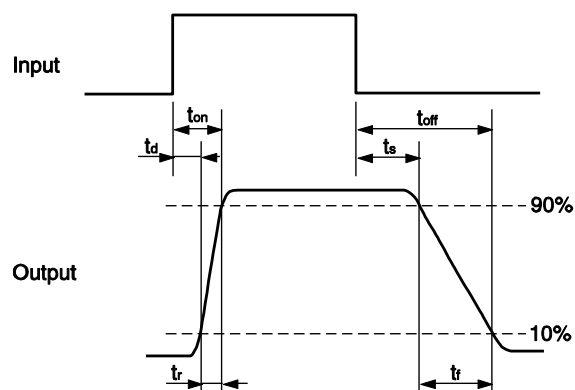
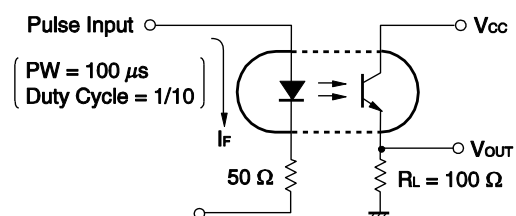
D : 100 to 300 (%)

H : 80 to 160 (%)

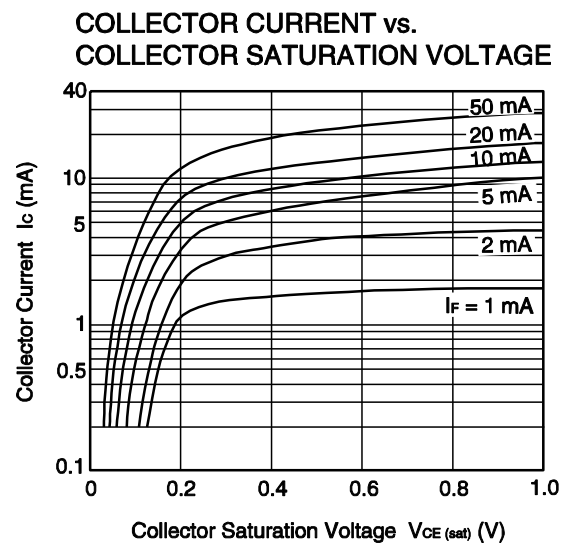
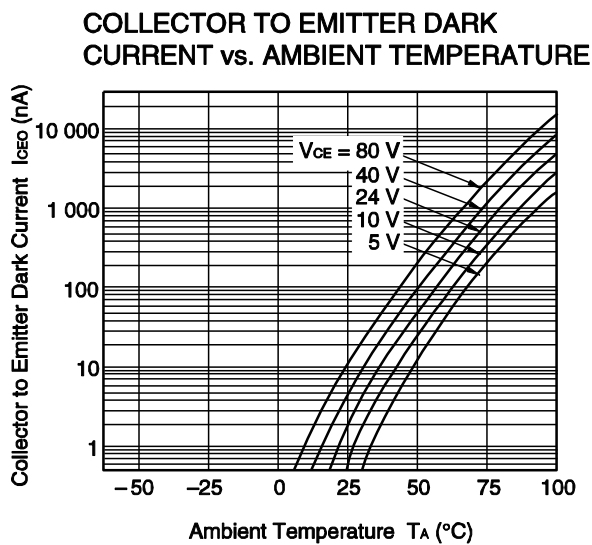
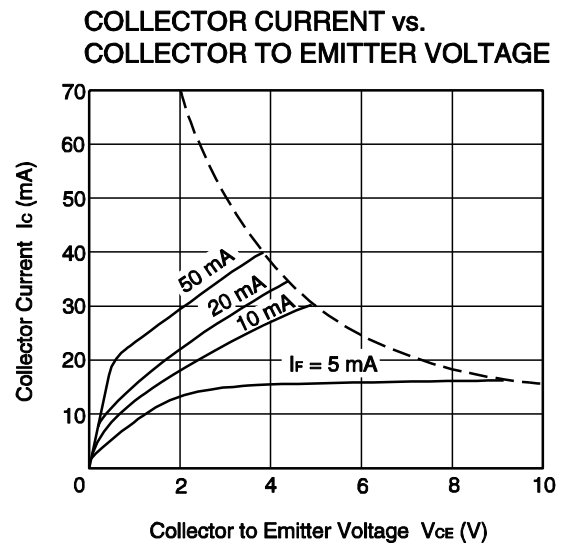
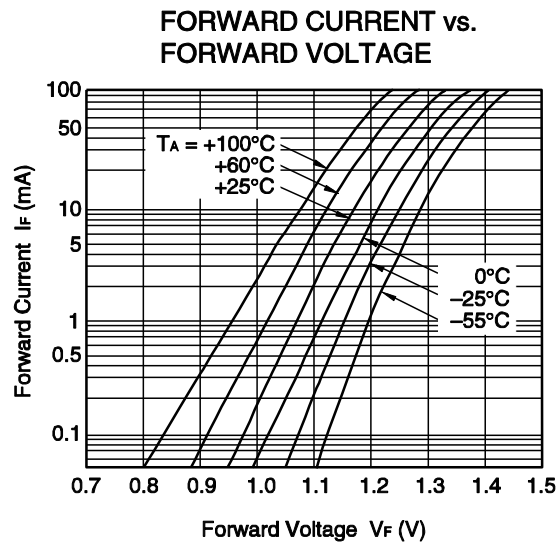
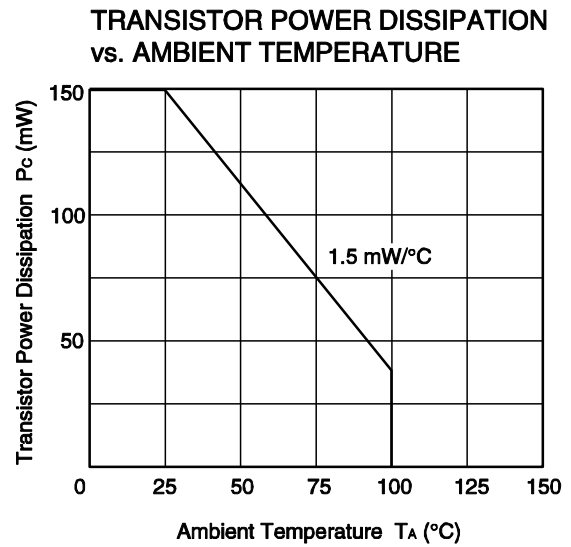
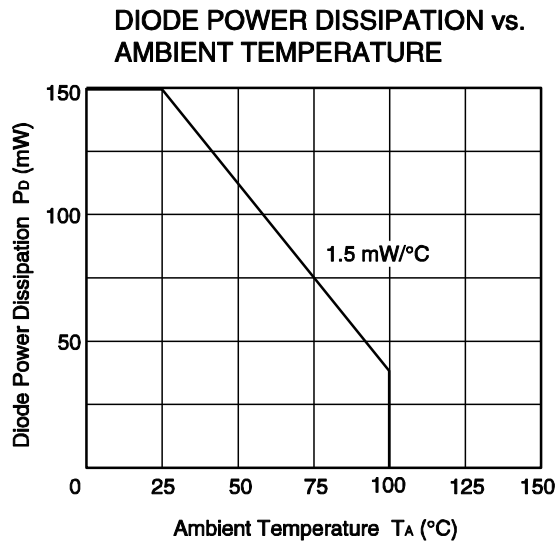
W : 130 to 260 (%)

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*2 Test circuit for switching time

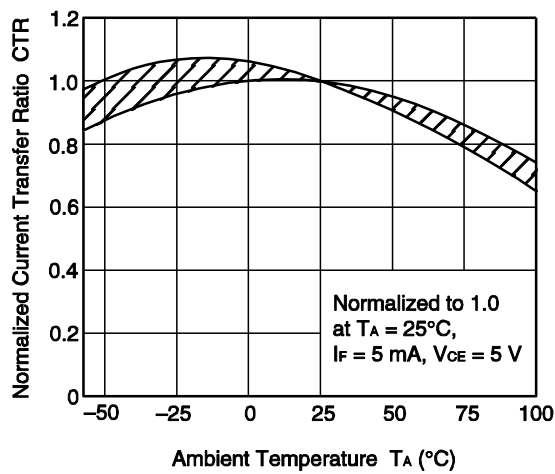


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

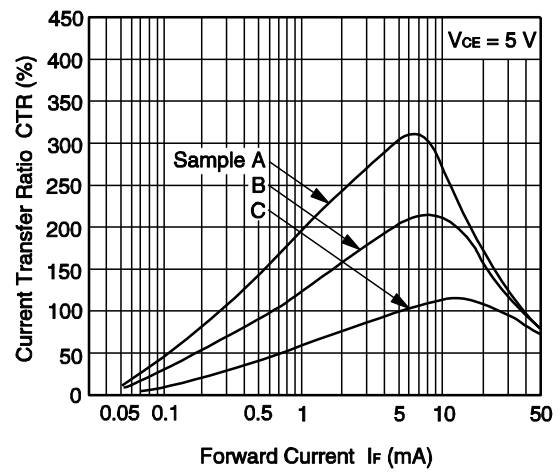


Remark The graphs indicate nominal characteristics.

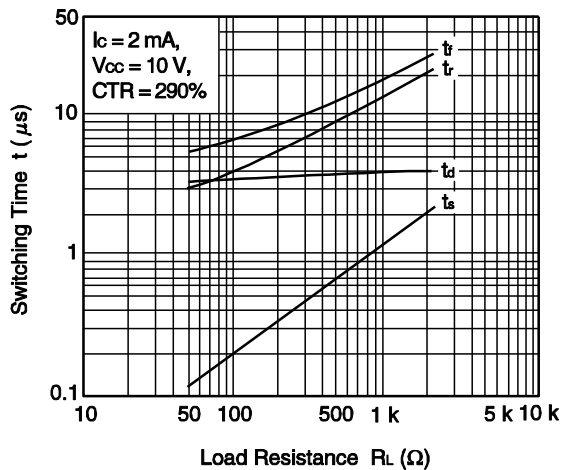
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



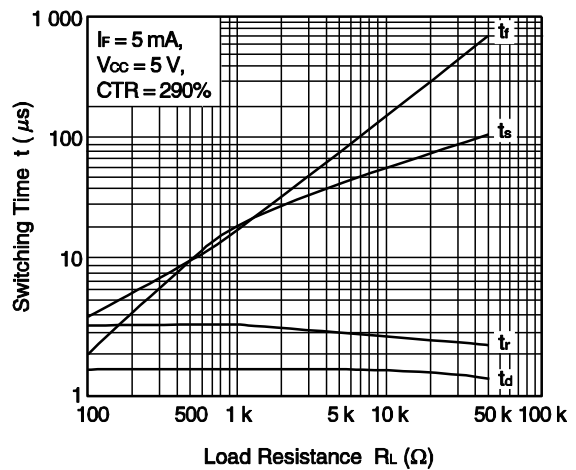
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



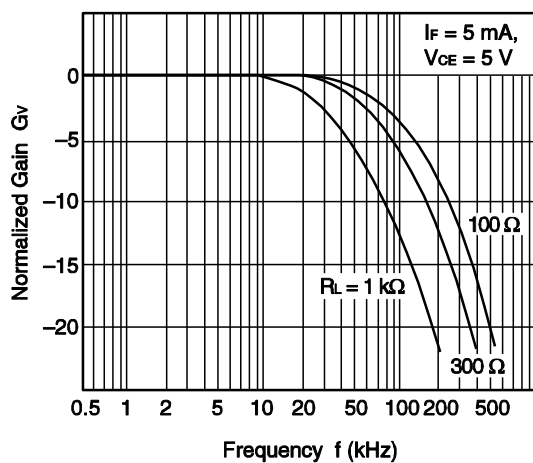
SWITCHING TIME vs. LOAD RESISTANCE



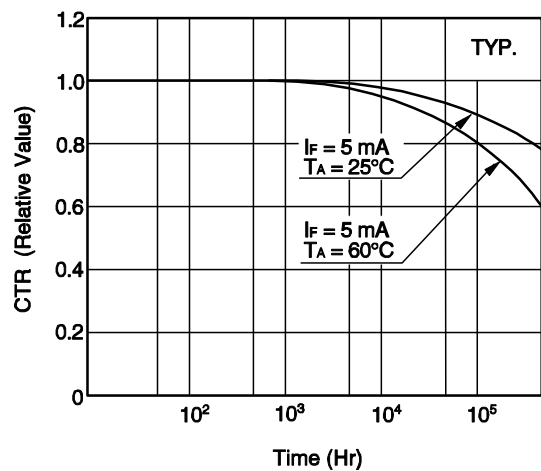
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



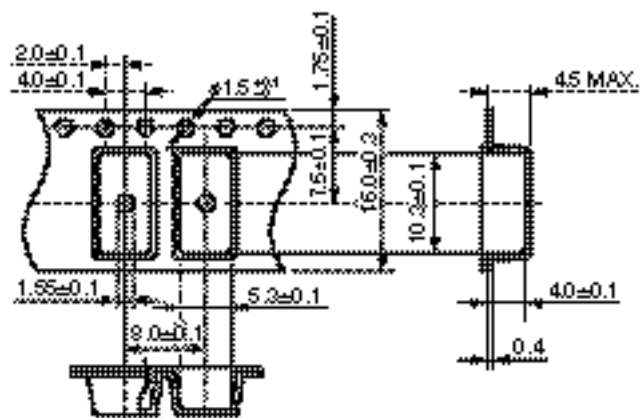
LONG TERM CTR DEGRADATION



Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT : mm)

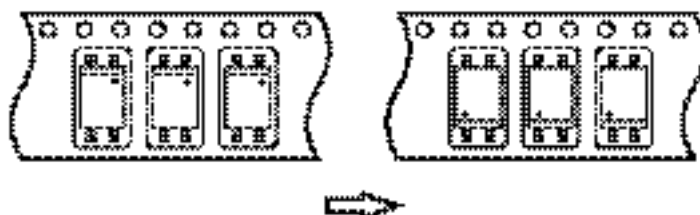
Outline and Dimensions (Tape)



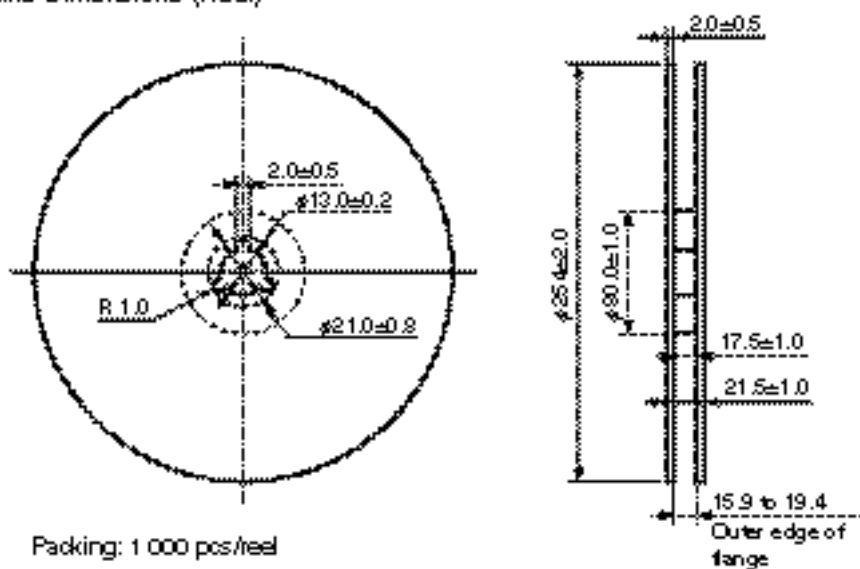
Tape Direction

PS2561L-1-E3

PS2561L-1-E4

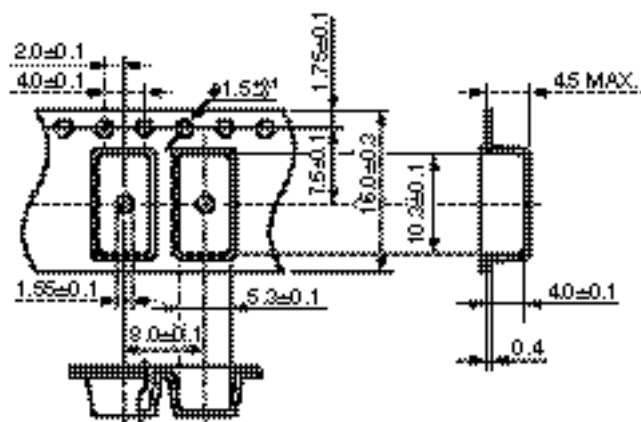


Outline and Dimensions (Reel)

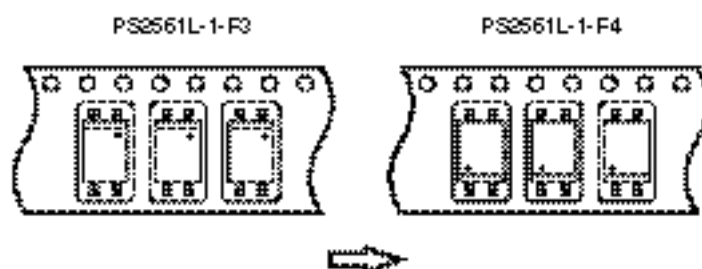


Packing: 1 000 pcs/reel

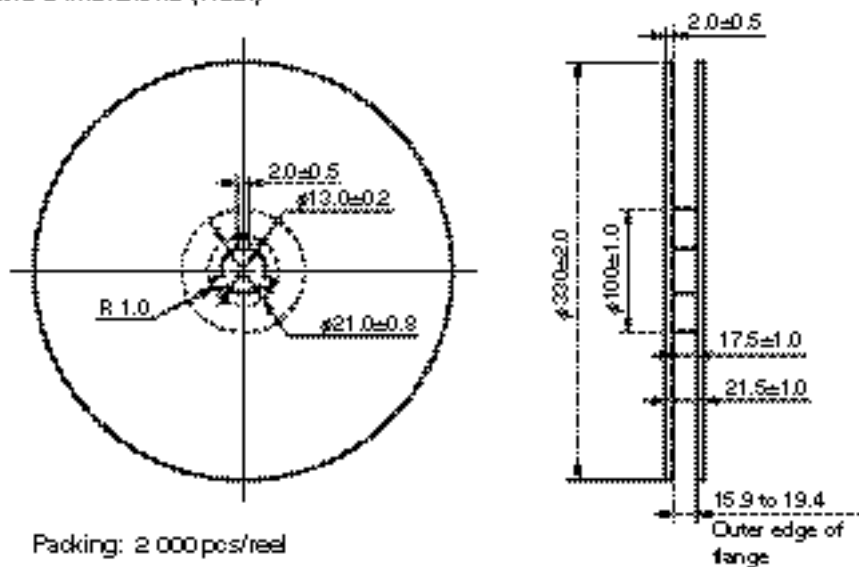
Outline and Dimensions (Tape)



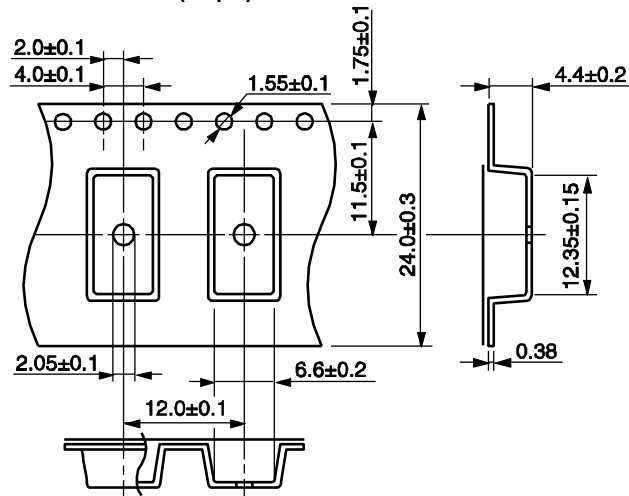
Tape Direction



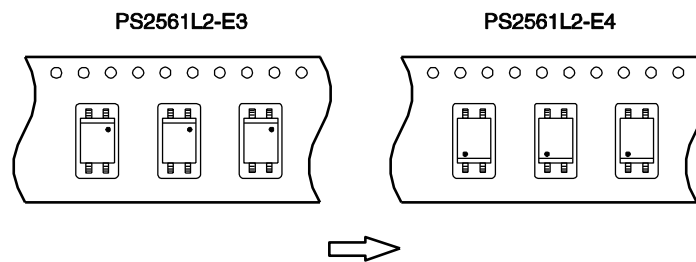
Outline and Dimensions (Reel)



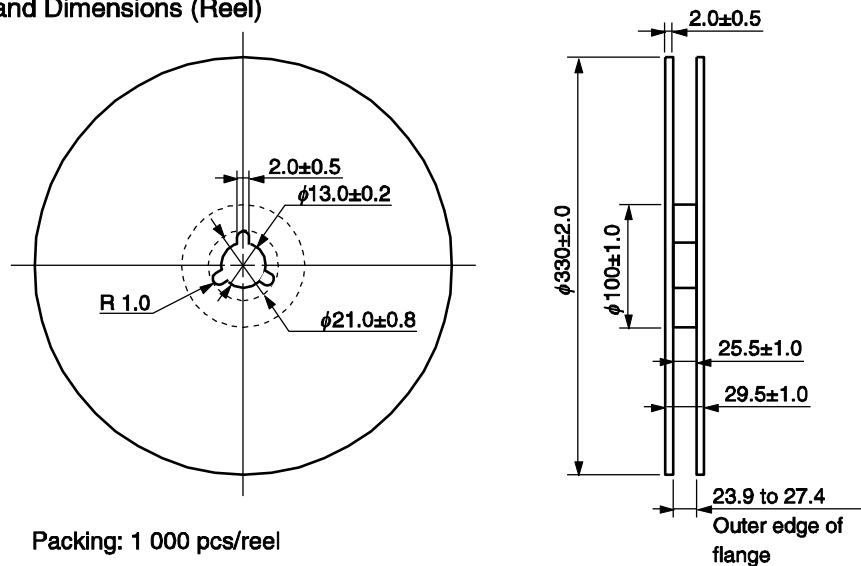
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

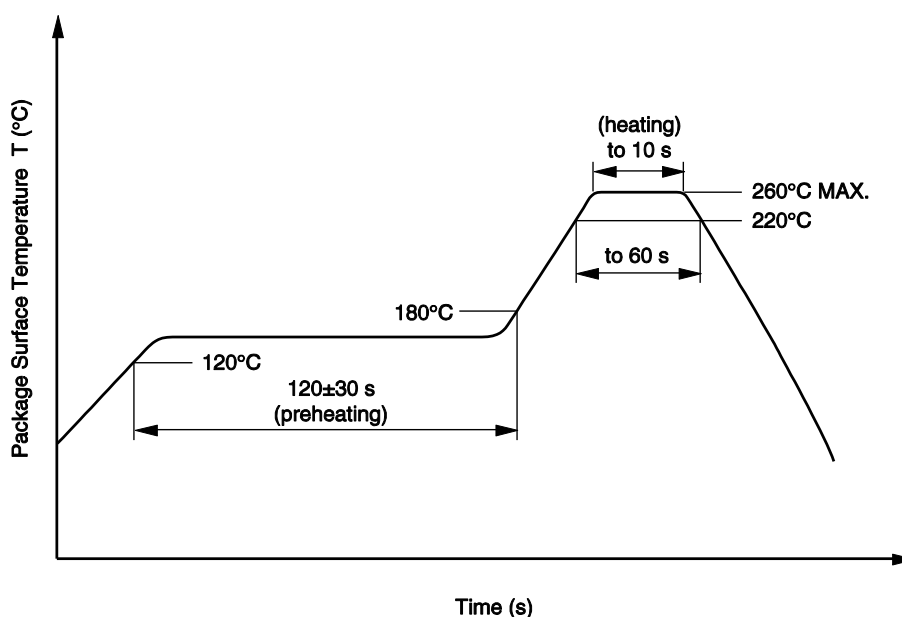
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below $I_F = 1$ mA.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

<R> SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}$, $P_d < 5 \text{ pC}$	U_{IORM} U_{pr}	890 1 335	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5 \text{ pC}$	U_{pr}	1 669	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Clearance distance		>7.0	mm
Creepage distance		>7.0	mm
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +150	°C
Operating temperature range	T_A	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc}$ at $T_A = 25^\circ\text{C}$ $V_{IO} = 500 \text{ V dc}$ at $T_A \text{ MAX.}$ at least 100°C	$R_{is \text{ MIN.}}$ $R_{is \text{ MIN.}}$	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , $P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500 \text{ V dc}$ at $T_A = T_{si}$	T_{si} I_{si} P_{si} $R_{is \text{ MIN.}}$	175 400 700 10^9	°C mA mW Ω

- **The information in this document is current as of December, 2008. The information is subject to change without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.**
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Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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